03-06-2003

FORM PTO-1595 RE 102382731 T

U.S. DEPARTMENT OF COMMERCE
Patent and Trademark Office

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies): 2·20·03

Hendrik T. Mau
Anuj Trivedi

Additional name(s) of conveying parties attached? ___ Yes _X_ No

2. Name and address of receiving party(ies):

Name Sun Microsystems, Inc.
Internal Address
Street Address 4120 Network Circle, MS SCA-120203
City Santa Clara State CA Zip 95054
Additional name(s) & address(es) attached? __ Yes _X_ No

JC997 U.S. PTO
10/371094
02/20/03

3. Nature of conveyance:

X Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Other ________

Execution Date February 14, 2003

4. Application number(s) or patent number(s): 10371094

If this document is being filed together with a new application, the execution date of the application is February 20, 2003

A. Patent Application No. (s) B. Patent No. (s)

Additional numbers attached? ☐ Yes X No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name Thelen Reid & Priest LLP
Internal Address
02/27/2003 AADOF01 00000015 10371094
04 FC:8021 40.00 OP
Street Address P. O. Box 640640
City San Jose State CA Zip 95164-0640

6. Total number of applications and patents involved 1

7. Total fee (37 CFR §3.41) .... $ 40.00

X Enclosed
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8. Deposit account number:

50-1698

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9. Statement and signature

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

William E. Winters
Name of Person Signing

Signature

2/20/03
Date

Total number of pages including cover sheet, attachments and document 4

Mail documents to be recorded with required cover sheet information to:
Commissioner of Patents & Trademarks, Box Assignments, Washington, DC 20231

~~02/27/2003 AADOF01 00000015 10371094~~

Docket No. SUN-P8414
811173-311

ASSIGNMENT

WHEREAS, we, Hendrik T. Mau, a citizen of Germany, residing at 2040 Larsen Place, and Anuj Trivedi, a citizen of India, residing at 353 Kiely Blvd., #A310, San Jose, CA 95129, have invented a "Electromigration Risk Analysis in Integrated Circuit Power Interconnect Systems Using Pseudo Dynamic Simulation" for which we have executed application papers for a U.S. patent thereon which is being filed concurrently herewith; and

WHEREAS, Sun Microsystems, Inc., a Delaware corporation, having a place of business located at 4120 Network Circle, MS SCA12-203, Santa Clara, CA 95054, is desirous of acquiring the exclusive right, title and interest in and to said invention and in and to the Letters Patent to be granted and issued therefor in the United States of America and its territories and possessions, and all countries foreign thereto;

NOW, THEREFORE, for a valuable consideration, the receipt of which is hereby acknowledged, we, Hendrik T. Mau and Anuj Trivedi, do sell, assign, transfer and set over unto the said Sun Microsystems, Inc., its successors and assigns, the full and exclusive right, title and interest in and to said invention, and in and to any and all Letters Patent to be granted and issued therefor, not only for, to and in the United States of America, its territories and possessions, but also for, to and in all other countries including all priority rights under the International Convention; and we hereby authorize and request the Commissioner of Patents and Trademarks to issue said Letters Patent to said Sun Microsystems, Inc., its successors and assigns, in accordance with this Assignment.

Docket No.

ASSIGNMENT CONTINUATION

Re: U.S. Patent Application entitled: Electromigration Risk Analysis in Integrated Circuit Power Interconnect Systems Using Pseudo Dynamic Simulation
Inventor: Hendrik T. Mau
Filing date: Herewith

WITNESS MY HAND at Sunnyvale, California, this 14th day of February, 2003

Hendrik T. Mau

ASSIGNMENT CONTINUATION

Re: U.S. Patent Application entitled: Electromigration Risk Analysis in Integrated Circuit Power Interconnect Systems Using Pseudo Dynamic Simulation
Inventor: Anuj Trivedi
Filing date: 02/14/03

WITNESS MY HAND at Sunny Vale, California, this 14th day of February, 2003

Anuj Trivedi